PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4828944

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JINJING JIANG	04/13/2017
LIWEN CHU	04/13/2017
LEI WANG	05/21/2017
YAKUN SUN	04/13/2017
HONGYUAN ZHANG	04/13/2017
HUI-LING LOU	06/01/2017

RECEIVING PARTY DATA

Name:	MARVELL SEMICONDUCTOR, INC.
Street Address:	5488 MARVELL LANE
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15488281

CORRESPONDENCE DATA

Fax Number: (408)222-2755

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 408-222-2500
Email: lgalang@marvell.com
Correspondent Name: KELVIN VIVIAN
Address Line 1: 5488 MARVELL LANE
Address Line 4: SANTA CLARA, CALIFORNIA 95054

ATTORNEY DOCKET NUMBER:	MP6643
NAME OF SUBMITTER:	KELVIN VIVIAN
SIGNATURE:	/Kelvin Vivian/
DATE SIGNED:	02/17/2018
Total Attachments: 5	

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ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, each of us, the undersigned,

Jinjing Jiang, Liwen Chu, Lei Wang, Yakun Sun, Hongyuan Zhang, and Hui-Ling Lou

who have created a certain invention for which an application for United States Letters Patent was executed by each of us concurrently herewith and entitled:

LINK LAYER SERVICE PLATFORM

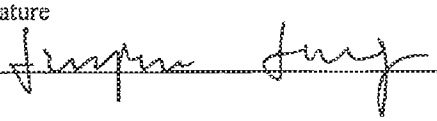
Does hereby sell, assign and transfer to Marvell Semiconductor, Inc., a corporation of California, having a place of business at 5488 Marvell Lane, Santa Clara, CA 95054, its successors, assigns, and legal representatives, the full and exclusive right to said invention and said application and to any and all inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;

Does hereby further sell, assign and transfer to Marvell Semiconductor, Inc., its successors, assigns, and legal representatives, the full and exclusive right to United States Provisional Patent Application No. 62/322,727, filed April 14, 2016, entitled Link Layer Service Platform, and to any and all inventions described in said provisional patent application(s) for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be entitled to the benefit thereof in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;

Agrees that Marvell Semiconductor, Inc., hereinafter referred to as Assignee, may apply for and receive Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said invention and for vesting title to said invention and all applications for patents on said invention in said Assignee, its successors, assigns, or legal representatives; and

Covenants with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

IN TESTIMONY WHEREOF we have hereunto set our signatures on the date(s) indicated below.

Full Name of First Inventor: Jinjing Jiang	
Inventor's Signature 	Date: Month/Day/Year 4/13/2017

Full Name of Second Inventor: Liwen Chu	
Inventor's Signature	Date: Month/Day/Year 04/13/17

Full Name of Third Inventor: Lei Wang	
Inventor's Signature	Date: Month/Day/Year

Full Name of Fourth Inventor: Yakun Sun	
Inventor's Signature	Date: Month/Day/Year

Full Name of Fifth Inventor: Hongyuan Zhang	
Inventor's Signature	Date: Month/Day/Year 4/13/17

Full Name of Sixth Inventor: Hui-Ling Lou	
Inventor's Signature	Date: Month/Day/Year

Accepted on behalf of:

MARVELL SEMICONDUCTOR, INC.

By: _____
Kelvin Vivian
Director, Intellectual Property

Date: 06/05/17

Full Name of Second Inventor: Liwen Chu	
Inventor's Signature	Date: Month/Day/Year

Full Name of Third Inventor: Lei Wang	
Inventor's Signature	Date: Month/Day/Year 5/21/17

Full Name of Fourth Inventor: Yakun Sun	
Inventor's Signature	Date: Month/Day/Year

Full Name of Fifth Inventor: Hongyuan Zhang	
Inventor's Signature	Date: Month/Day/Year

Full Name of Sixth Inventor: Hui-Ling Lou	
Inventor's Signature	Date: Month/Day/Year

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Inventor's Signature	Date: Month/Day/Year

Full Name of Third Inventor: Lei Wang	
Inventor's Signature	Date: Month/Day/Year

Full Name of Fourth Inventor: Yakun Sun	
Inventor's Signature	Date: Month/Day/Year 4/13/2017

Full Name of Fifth Inventor: Hongyuan Zhang	
Inventor's Signature	Date: Month/Day/Year

Full Name of Sixth Inventor: Hui-Ling Lou	
Inventor's Signature	Date: Month/Day/Year

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Kelvin Vivian
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Date: 06/05/17

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Inventor's Signature	Date: Month/Day/Year

Full Name of Fourth Inventor: Yakun Sun	
Inventor's Signature	Date: Month/Day/Year

Full Name of Fifth Inventor: Hongyuan Zhang	
Inventor's Signature	Date: Month/Day/Year

Full Name of Sixth Inventor: Hui-Ling Lou	
Inventor's Signature	Date: Month/Day/Year 6/1/17

Accepted on behalf of:

MARVELL SEMICONDUCTOR, INC.

By: _____
Kelvin Vivian
Director, Intellectual Property

Date: 6/05/17